

RoHS Compliant Product
A suffix of "-C" specifies halogen free

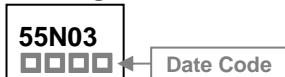
DESCRIPTION

The SID55N03 provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness. The TO-252 package is universally preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters.

FEATURES

- Dynamic dv/dt Rating
- Simple Drive Requirement
- Repetitive Avalanche Rated
- Fast Switching

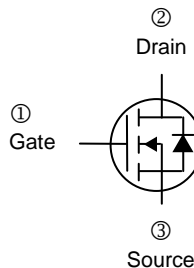
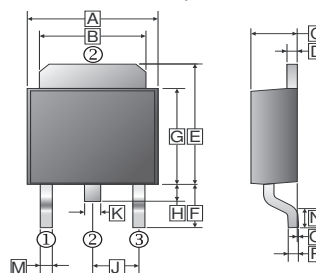
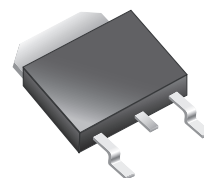
MARKING



PACKAGE INFORMATION

Package	MPQ	LeaderSize
TO-252	2.5K	13' inch

TO-252(D-Pack)



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	6.4	6.8	J	2.30	REF.
B	5.20	5.50	K	0.70	0.90
C	2.20	2.40	M	0.50	1.1
D	0.45	0.58	N	0.9	1.6
E	6.8	7.3	O	0	0.15
F	2.40	3.0	P	0.43	0.58
G	5.40	6.2			
H	0.8	1.20			

ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	25	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	$T_C=25^\circ\text{C}$	55
		$T_C=100^\circ\text{C}$	35
Pulsed Drain Current ¹	I_{DM}	215	A
Total Power Dissipation	P_D	62.5	W
Linear Derating Factor		0.5	W / $^\circ\text{C}$
Single Pulse Avalanche Energy ²	E_{AS}	240	mJ
Single Pulse Avalanche Current	I_{AS}	31	A
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55~150	$^\circ\text{C}$
Thermal Resistance Rating			
Maximum Thermal Resistance Junction-Ambient	$R_{\theta JA}$	110	$^\circ\text{C} / \text{W}$
Maximum Thermal Resistance Junction-Case	$R_{\theta JC}$	2.0	$^\circ\text{C} / \text{W}$

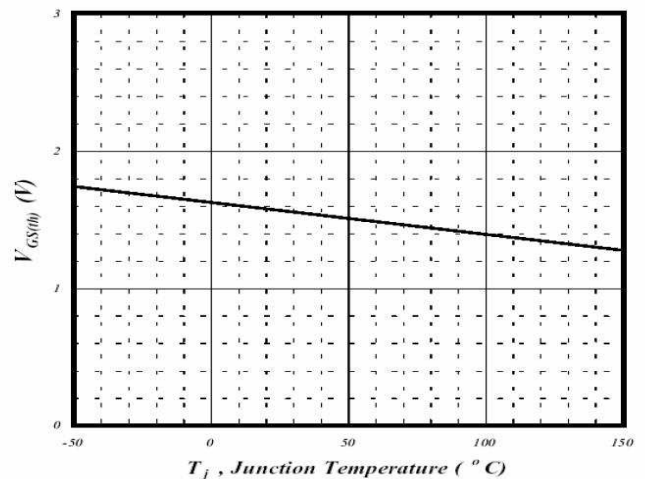
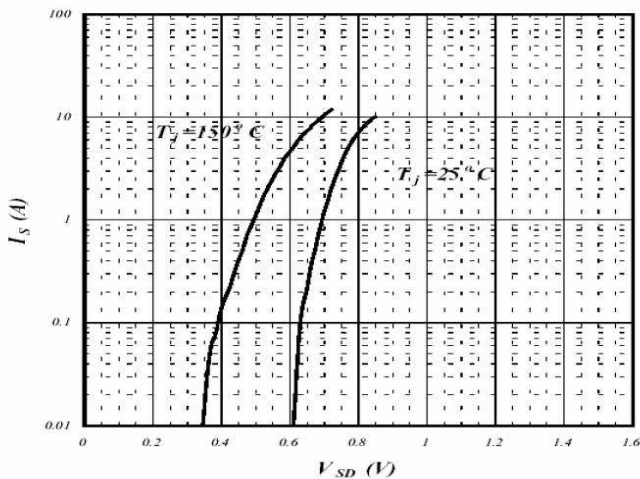
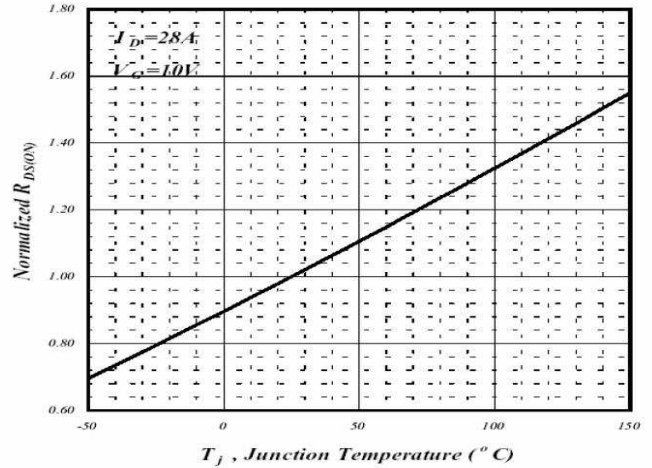
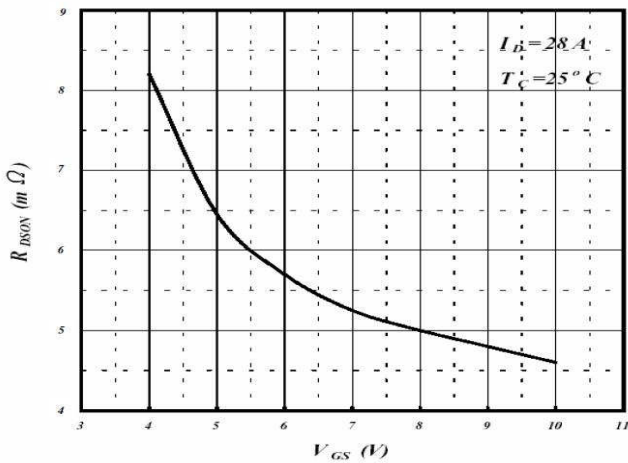
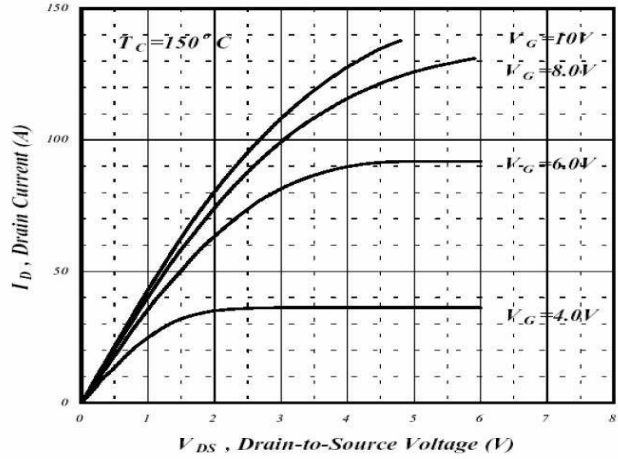
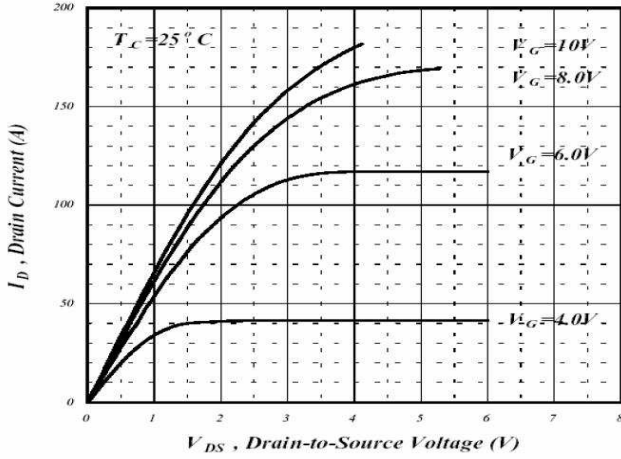
ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions	
Static							
Drain-Source Breakdown Voltage	BV_{DSS}	25	-	-	V	$V_{GS}=0, I_D=250\mu\text{A}$	
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS} / \Delta T_J$	-	0.037	-	V/ $^\circ\text{C}$	Reference to 25°C , $I_D=1\text{mA}$	
Gate-Threshold Voltage	$V_{GS(th)}$	1.0	-	3.0	V	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	
Forward Transconductance	g_{fs}	-	30	-	S	$V_{DS}=10\text{V}, I_D=28\text{A}$	
Gate-Source Leakage Current	I_{GSS}	-	-	± 100	nA	$V_{GS} = \pm 20\text{V}$	
Drain-Source Leakage Current	I_{DSS}	$T_J = 25^\circ\text{C}$	-	-	1	μA	$V_{DS}=25\text{V}, V_{GS}=0$
		$T_J = 150^\circ\text{C}$	-	-	25	μA	$V_{DS}=20\text{V}, V_{GS}=0$
Static Drain-Source On-Resistance ³	$R_{DS(ON)}$	-	4.5	6	m Ω	$V_{GS}=10\text{V}, I_D=30\text{A}$	
		-	7	9		$V_{GS}=4.5\text{V}, I_D=30\text{A}$	
Total Gate Charge ³	Q_g	-	16.8	-	nC	$I_D=28\text{A}$ $V_{DS}=20\text{V}$ $V_{GS}=5\text{V}$	
Gate-Source Charge	Q_{gs}	-	6.0	-			
Gate-Drain ("Miller") Charge	Q_{gd}	-	4.9	-			
Turn-on Delay Time ³	$T_{d(on)}$	-	15.1	-	nS	$V_{DS}=15\text{V}$ $I_D=28\text{A}$ $V_{GS}=10\text{V}$ $R_G=3.3\Omega$ $R_D=0.53\Omega$	
Rise Time	T_r	-	4	-			
Turn-off Delay Time	$T_{d(off)}$	-	45.2	-			
Fall Time	T_f	-	7.6	-			
Input Capacitance	C_{ISS}	-	2326	-	pF	$V_{GS}=0$ $V_{DS}=25\text{V}$ $f=1.0\text{MHz}$	
Output Capacitance	C_{OSS}	-	331	-			
Reverse Transfer Capacitance	C_{RSS}	-	174	-			
Source-Drain Diode							
Diode Forward Voltage ³	V_{SD}	-	-	1.5	V	$I_S=20\text{A}, V_{GS}=0, T_J=25^\circ\text{C}$	
Continuous Source Current (Body Diode)	I_S	-	-	55	A	$V_D=V_G=0, V_S=1.5\text{V}$	

Notes:

- Pulse width limited by safe operating area.
- Starting $T_J=25^\circ\text{C}$, $V_{DD}=20\text{V}$, $L=0.1\text{mH}$, $R_G=25$, $I_{AS}=10\text{A}$.
- Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

CHARACTERISTIC CURVES



CHARACTERISTIC CURVES

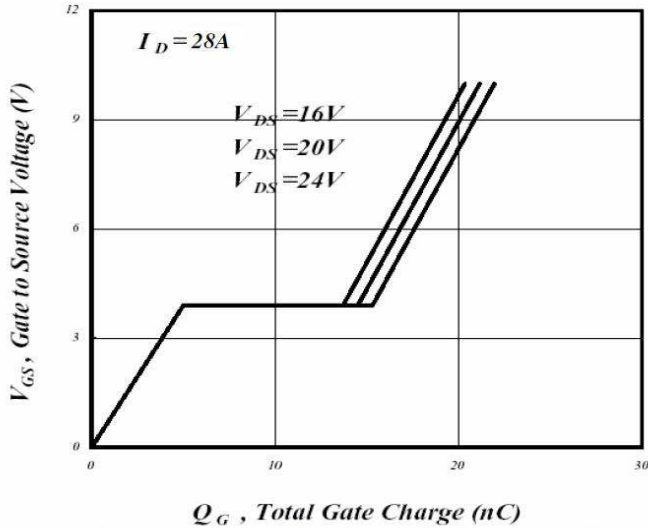


Fig 7. Gate Charge Characteristics

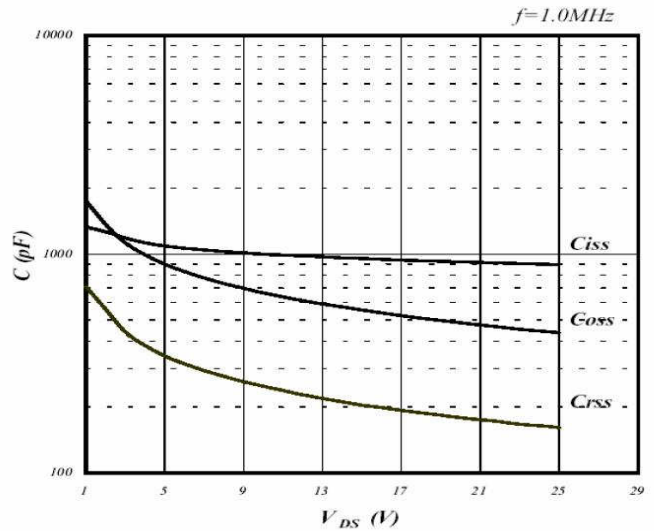


Fig 8. Typical Capacitance Characteristics

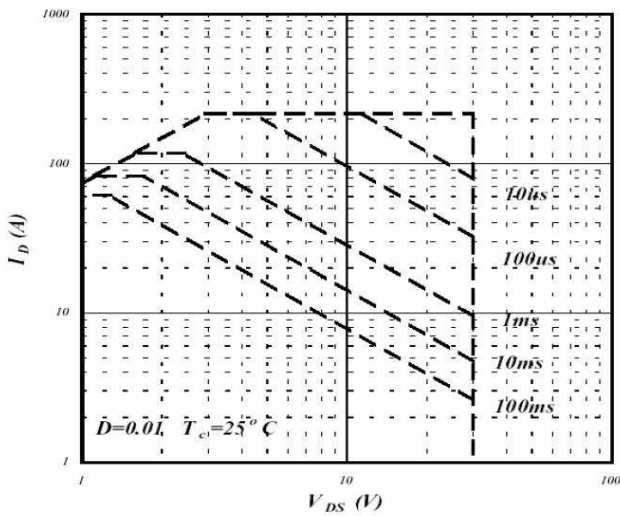


Fig 9. Maximum Safe Operating Area

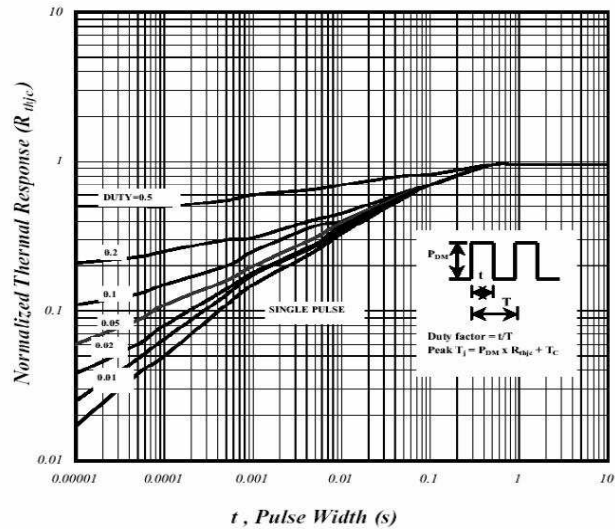


Fig 10. Effective Transient Thermal Impedance

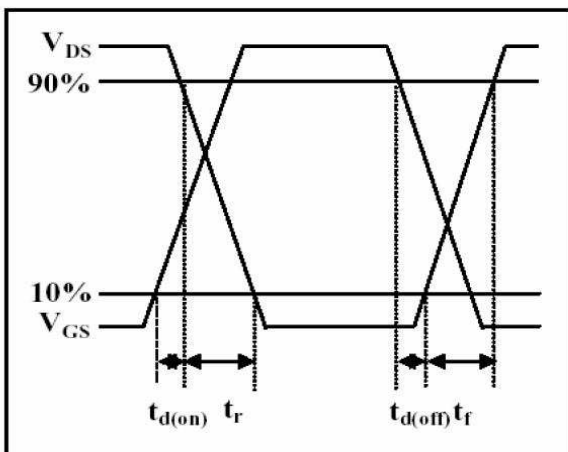


Fig 11. Switching Time Waveform

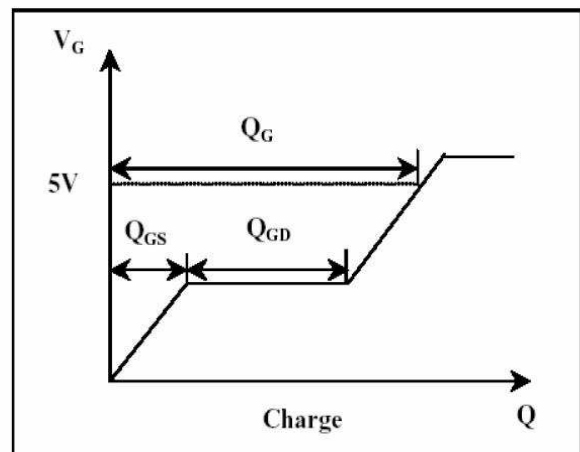


Fig 12. Gate Charge Waveform